

	<a href="#"><u>10 GHz Bandwidth Socket for 10 Lead ODFN Package</u></a> September 2011
	<a href="#"><u>Production test Socket for ASE's 32 ld QFN with ePad</u></a> August 2011
	<a href="#"><u>8 GHz Bandwidth Socket for ST Micro's 616FPBGA</u></a> July 2011
	<a href="#"><u>Stamped Spring Pin BGA Socket for LTE Femtocell SoCs</u></a> June 2011
	<a href="#"><u>Stamped Spring Pin Socket for Amkor's 24 ld QFN with Exposed Pad Technology</u></a> May 2011
	<a href="#"><u>40 GHz Bandwidth Socket for STM's PBGA521</u></a> May 2011
	<a href="#"><u>Triple Stacked Spring Pin Socket for Processor, Memory &amp; Memory Probe</u></a> April 2011
	<a href="#"><u>8 GHz Bandwidth Socket for Intel's ICH6 (I/O Controller Hub 6) BGA Package</u></a> April 2011

	<a href="#"><u>Stamped Spring Pin BGA Socket for IDT's FCBGA144</u></a> March 2011
	<a href="#"><u>Elastomer Socket for Infineon's BGA221</u></a> March 2011
	<a href="#"><u>GHz Bandwidth Socket for Dual WLCSP</u></a> February 2011
	<a href="#"><u>Prototype and Debug 96 ball BGA with Ease</u></a> February 2011
	<a href="#"><u>Stamped Spring Pin BGA Socket for Burn-in Characterization</u></a> January 2011
	<a href="#"><u>ATE Spring Pin BGA Socket for Digital Camera Processor</u></a> January 2011
	<a href="#"><u>Spring Pin Socket for Kelvin Resistance Measurement</u></a> December 2010
	<a href="#"><u>Package Converters Enable Testing Generation I product on Generation II System</u></a> November 2010
	<a href="#"><u>Elastomer Socket for High Bandwidth 0.4mm Pitch 144TQFP</u></a> November 2010

	<p><a href="#"><u>GHz Bandwidth Socket for Embedded Camera Module PMU</u></a> October 2010</p>
	<p><a href="#"><u>GHz Bandwidth Socket for Thermal Characterization</u></a> October 2010</p>
	<p><a href="#"><u>Actel Device Converter Allow Axcelerator® FPGAs to be used in PCBs designed for Radiation-Tolerant FPGAs</u></a> September 2010</p>
	<p><a href="#"><u>Etched Spring Pin Socket for Capacitive Touch-key Sensor QFN used in Smart Phones</u></a> September 2010</p>
	<p><a href="#"><u>Xilinx Device Converter Allow Reliable Conversion to Upgraded Modules</u></a> August 2010</p>
	<p><a href="#"><u>Stamped Spring Pin Socket for Dual Channel High Performance UART</u></a> August 2010</p>
	<p><a href="#"><u>GHz Bandwidth Socket for Infineon's Single Chip Mobile IC</u></a> July 2010</p>
	<p><a href="#"><u>Double Stacked Spring Pin Socket for Processor and Memory</u></a> June 2010</p>
	<p><a href="#"><u>Multi Level GHz Bandwidth Socket for Memory Probing</u></a> June 2010</p>
	<p><a href="#"><u>10 GHz Clamshell Socket for 0.4mm Pitch BGA Packages</u></a> May 2010</p>



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